

Gleichmann & Co. Electronics GmbH Industriestrasse 16 76297 Stutensee-Spöck / Germany

**CUSTOMER:** 

### **SPECIFICATION**

MODULE NO.:				GE-	0128640	2-TFH/R
		VED BY MER USE ON	LY)	PCB VI	ERSION:	DATA:
SALES I	ВҮ	APPROVE	D BY	C	HECKED BY	PREPARED BY
ISSUE	D					
DATE	•					
VERSION		DATE		ISED E NO.	SUMMARY	
A	200	09.02.20			Correct I	C=ST7565P



1			
REC	CORDS OF RE	DOC. FIRST ISSUE	
VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2009/1/15		First issue
A	2009.02.20		Correct IC=ST7565P

# **Contents**

- 1. Module classification information
- 2. Precautions in Use of LCD Modules
- 3. General Specification
- 4. Absolute Maximum Ratings
- 5. Electrical Characteristics
- 6. Optical Characteristics
- 7. Interface Pin Function
- 8. Counter Drawing and Block Diagram
- 9. Timing Characteristics
- 10. Reliability
- 11. Backlight Information
- 12. Inspection specification
- 13. Material List of Components for RoHs

# 1. Module Classification Information

	0 2 3 4 5 6 7 8						
1	Brand: Gleichmann Electronics						
2	Display Type : C→Character Type, G→Graphic Type, O→COG Type						
3	Display Font: 128 * 64 dots						
4	Model serials no.						
(5)	Backlight Type:	N→Without backlight	T→LED, White				
		B→EL, Blue green	A→LED, Amber				
		D→EL, Green R→LED, Red					
		W→EL, White O→LED, Orange					
		F→CCFL, White G→LED, Green					
		$Y\rightarrow$ LED, Yellow Green $C\rightarrow$ LED, RGB					
6	LCD Mode:	B→TN Positive, Gray	T→FSTN Negative				
		N→TN Negative,					
		G→STN Positive, Gray					
		Y→STN Positive, Yellow Green					
		M→STN Negative, Blue					
		F→FSTN Positive					
7	LCD Polarizer Type/	A→Reflective, N.T, 6:00	H→Transflective, W.T,6:00				
	Temperature range/	D→Reflective, N.T, 12:00	K→Transflective, W.T,12:00				
	View direction	G→Reflective, W. T, 6:00	C→Transmissive, N.T,6:00				
		J→Reflective, W. T, 12:00	F→Transmissive, N.T,12:00				
		B→Transflective, N.T,6:00	I→Transmissive, W. T, 6:00				
		E→Transflective, N.T.12:00	L→Transmissive, W.T,12:00				
8	Special Code	/R: Fit in with the RoHS directions	and regulations				

## 2. Precautions in Use of LCD Module

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD Module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage:pleasse storage in anti-static electricity container and clean environment.

## 3. General Specification

Item	Dimension	Unit
Number of Characters	128 x 64 dots	_
Module dimension	55.2x 39.8 x 6.5(MAX)	mm
View area	45.2 x 27.0	mm
Active area	40.92 x 24.28	mm
Dot size	0.28 x 0.34	mm
Dot pitch	0.32 x 0.38	mm
LCD type	FSTN Positive Transflective (In LCD production, It will occur slightly cocan only guarantee the same color in the same	
Duty	1/64 , 1/9 Bias	
View direction	6 o'clock	
Backlight Type	LED White	

# 4. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	$T_{OP}$	-20		+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{ST}$	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	$V_{\rm I}$	-0.3	_	V <sub>DD</sub> +0.3	V
Supply Voltage For Logic	$V_{ m DD} ext{-}V_{ m SS}$	-0.3		5.0	V
LCD Driver Supply Voltage	$ m V_{OUT}$	4		13	V

# **5.Electrical Characteristics**

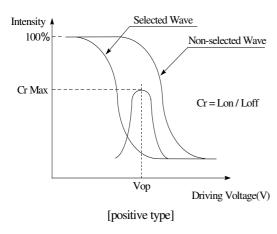
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$	_	2.7	3.0	3.3	V
		Ta=-20°C	9.1	9.3	9.5	V
Supply Voltage For LCM	$V_{DD}$ - $V_5$	Ta=25°C	8.8	9.0	9.2	V
		Ta=70°C	8.6	8.8	9.0	V
Input High Volt.	$V_{\mathrm{IH}}$	_	$0.8 V_{DD}$		$V_{\mathrm{DD}}$	V
Input Low Volt.	$V_{\mathrm{IL}}$	_	Vss	_	$0.2\mathrm{V_{DD}}$	V
Output High Volt.	$V_{OH}$	_	$0.8~\mathrm{V_{DD}}$		$V_{DD}$	V
Output Low Volt.	$V_{OL}$	_	Vss		$0.2V_{DD}$	V
Supply Current(No include LED Backlight)	$I_{DD}$	V <sub>DD</sub> =3.0V		0.49	1	mA

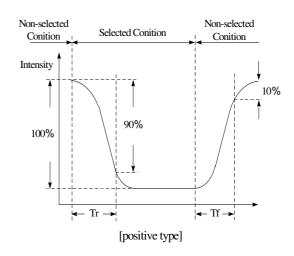
## **6.Optical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	$(V)\theta$	CR≧2	30	_	60	deg
view rangie	(H) φ	CR≧2	-45	_	45	deg
Contrast Ratio	CR	_	_	5	_	_
Response Time	T rise	_	_	230	330	ms
	T fall	_	_	170	270	ms

### **Definition of Operation Voltage (Vop)**

### **Definition of Response Time (Tr, Tf)**





### **Conditions:**

Operating Voltage: Vop

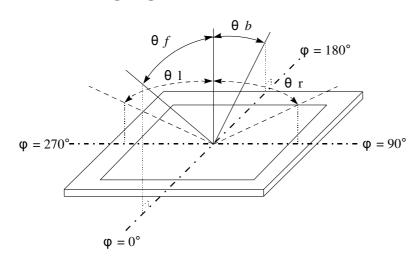
operating voltage: vop

Frame Frequency: 64 HZ

Viewing Angle( $\theta$ ,  $\varphi$ ):  $0^{\circ}$ ,  $0^{\circ}$ 

Driving Waveform: 1/N duty, 1/a bias

### Definition of viewing angle( $CR \ge 2$ )



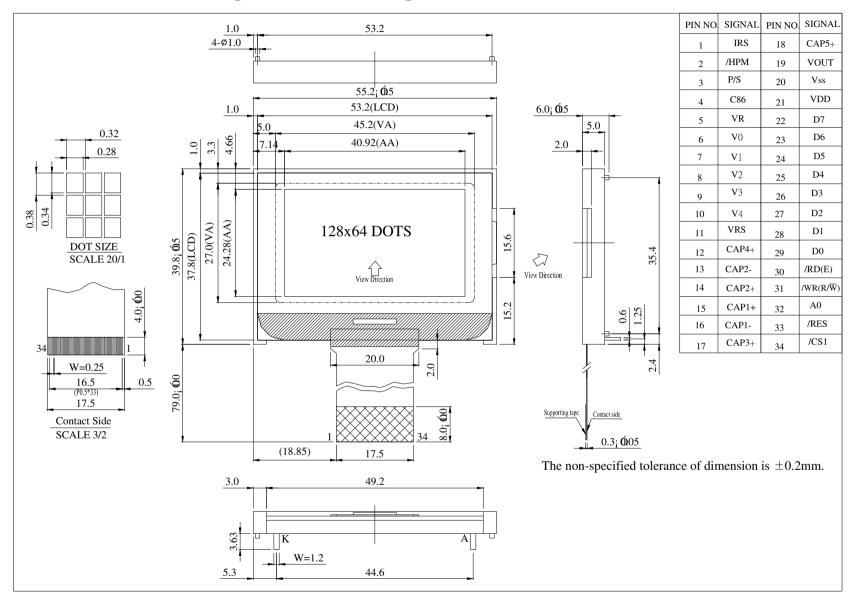
# **7.Interface Pin Function**

Pin No.	Symbol	Level	Description				
1	IRS		This terminal selects the resistors for the V5 voltage level adjustment.  IRS = "H": Use the internal resistors.  IRS = "L": Do not use the internal resistors.  The V5 voltage level is regulated by an external resistive voltage divider attached to the VR terminal. This pin is enabled only when the master operation mode is selected. It is fixed to either "H" or "L" when the slave operation mode is selected.				
2	/HPM		This is the power control terminal for the power supply circuit for liquid crystal drive.  HPM="H":Normal made HPM="L":High power mod				
3	P/S		This is the parallel data input/serial data input switch terminal. P/S = "H": Parallel data input. P/S = "L": Serial data input. The following applies depending on the PS status:    P/S   Data/Command   Data   Read/Write   Serial Clock     "H"   A0   DB0 ~ DB7   /RD, /WR   X     "L*   A0   SI (DB7)   Write only   SCL (DB6)    When P/S = "L", DB0 to DB5 fixed "H". /RD (EP) and /WR (RWP) are fixed to either "H" or "L". With serial data input, It is impossible read data from RAM .				
4	C86		This is the MPU interface switch terminal.  C86 = "H": 6800 Series MPU interface.  C86 = "L": 8080 MPU interface.				
5	VR		Output voltage regulator terminal. Provides the voltage between VDD and V5 through a resistive voltage divider. These are only enabled when the V5 voltage regulator internal resistors are not used (IRS = "L"). These cannot be used when the V5 voltage regulator internal resistors are used (IRS = "H").				
6	V0		This is a multi-level power supply for the liquid crystal drive.				
7	V1		The voltage Supply applied is determined by the liquid crystal cell, and is changed through the use of a resistive voltage				
8	V2		divided or through changing the impedance using an op. amp.				
9	V3		Voltage levels are determined based on Vss, and must maintain the relative magnitudes shown below.				

		$V0 \Box V1 \Box V2 \Box V4 \Box V_{22}$
		V0 $\Box$ V1 $\Box$ V2 $\Box$ V3 $\Box$ V4 $\Box$ Vss When the power supply turns ON, the internal power supply
		circuits produce the V1 to V4 voltages shown below. The
10	\/A	voltage settings are selected using the LCD bias set command.
10	V4	1/65 DUTY   1/49 DUTY   1/33 DUTY   1/55 DUTY   1/53 DUTY
		V1 8/9*V0.6/7*V0 7/8*V0.5/6*V0 5/6*V0 7/8*V0.5/6*V0 7/8*V0.5/6*V0
		V2 7/9*V0,5/7*V0 6/8*V0,4/6*V0 4/6*V0,3/5*V0 6/8*V0,4/6*V0 6/8*V0,4/6*V0 2/9*V0,2/7*V0 2/8*V0,2/6*V0 2/6*V0,2/5*V0 2/8*V0,2/6*V0 2/8*V0,2/6*V0
		V4 1/9*V0,1/7*V0 1/8*V0,1/6*V0 1/6*V0,1/5*V0 1/8*V0,1/6*V0 1/8*V0,1/6*V0
11	VRS	This is the internal-input VREG power supply for the lcd power supply
		DC/DC voltage converter. Connect a capacitor between this
12	CAP4+	terminal and the CAP2- terminal.
12	OADO	DC/DC voltage converter. Connect a capacitor between this
13	CAP2-	terminal and the CAP2+ terminal.
14	CAP2+	DC/DC voltage converter. Connect a capacitor between this
14	OAI 2+	terminal and the CAP2- terminal.
15	CAP1+	DC/DC voltage converter. Connect a capacitor between this
		terminal and the CAP1- terminal.
16	CAP1-	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1+ terminal.
		DC/DC voltage converter. Connect a capacitor between this
17	CAP3+	terminal and the CAP1- terminal
1.0	0.455	DC/DC voltage converter. Connect a capacitor between this
18	CAP5+	terminal and the CAP1- terminal.
19	VOUT	DC/DC voltage converter. Connect a capacitor between this
19	VO01	terminal and VSS
20	Vss	Power Supply (VSS=0)
21	VDD	Power Supply (VDD=3.0)
22	DB7	
23	DB6	
24	DB5	This is an 8-bit bi-directional data bus that connects to an 8-bit
25	DB4	or 16-bit standard MPU data bus.  When the serial interface is selected (PS = "I"), DB7 serves as
26	DB3	When the serial interface is selected (PS = "L"), DB7 serves as the serial data input terminal (SI) and DB6 serves as the serial
27	DDC	clock input terminal (SCL).
27	DB2	At the same time, DB5 - 0 are set to high impedance.
		When the chip select is inactive, DB0 to DB7 are set to high
28	DB1	impedance.
29	DB0	
		When connected to an 8080 MPU, this is LOW active.
		This pin is connected to the RD signal of the 8080 MPU, and
30	/RD(E)	the ST7565P series data bus is in an output status when this
		signal is "L". When connected to a 6800 Series MPU, this is
		active HIGH. This is the 6800 Serier MPU enable clock input terminal.
		This is the bood seriel wif o chable clock input terilinal.

31	/WR(RW)	When connected to an 8080 MPU, this is LOW active. This pin is connected to the RD signal of the 8080 MPU, and the ST7565P series data bus is in an output status when this signal is "L".  When connected to a 6800 Series MPU, this is active HIGH. This is the 6800 Serier MPU enable clock input terminal.
32	Α0	This is connect to the least significant bit of the normal MPU address bus, and it determines whether the data bits are data or a command.  A0 = "H": Indicates that DB0 to DB7 are display data.  A0 = "L": Indicates that DB0 to DB7 are control data.
33	/RES	/RES is set to "L", the settings are initialized. The /RES signal level performs the reset operation.
34	/CS1	This is the chip select signal. When /CS1 = "L", then the chip select becomes active, and data/command I/O is enabled.

## **8.Contour Drawing & Block Diagram**



# 9. Timing Characteristics

Please consult the spec of Sitronix ST7565P

## 10. Reliability

Content of Reliability Test (wide temperature, -20°C~70°C)

	Environmental Test							
Test Item	Content of Test	Test Condition	Note					
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2					
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2					
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs						
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1					
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2					
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles						
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for 15 minutes each	3					
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time						

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

## **11.Backlight Information**

### **Specification**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	43.2	48	75	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	
Reverse Voltage	VR	_	_	5	V	_
Luminous Intensity	IV	456.2	570	_	CD/M <sup>2</sup>	ILED=48mA
LED Life Time	_	_	50K	_	Hr.	ILED≤48mA
Color	White		I		l	-

Note: The LED of B/L is drive by current only; driving voltage is only for reference To make driving current in safety area (waste current between minimum and maximum).

Note1:50K hours is only an estimate for reference.

# 12. Inspection specification

NO	Item	Criterion			
01	Electrical Testing	<ol> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ol>			
02	Black or white spots on LCD (display only)	<ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> </ul>			
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi = (x + y)/2$ $X \qquad \qquad$	2.5		
		3.2 Line type : (As following drawing)  Length Width Acceptable Q TY $W \le 0.02$ Accept no dense $L \le 3.0  0.02 < W \le 0.03$ $L \le 2.5  0.03 < W \le 0.05$ $0.05 < W$ As round type	2.5		
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. Size $\Phi$ Accept no dense $0.20 < \Phi \le 0.20$ Accept no dense $0.20 < \Phi \le 0.50$ 3 $0.50 < \Phi \le 1.00$ 2 $1.00 < \Phi$ 0 Total QTY 3	2.5		

NO	Item	Criterion			
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
06	Chipped glass	Symbols Define: x: Chip length y: Ch k: Seal width t: Gla L: Electrode pad length 6.1 General glass chip 6.1.1 Chip on panel sur  z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$	nip width z: Chip thickr ass thickness a: LCD side n:	ness length  anels: $x: Chip length$ $x \le 1/8a$ $x \le 1/8a$	2.5
		⊙ If there are 2 or more chips, x is the total length of each chip.			

NO	Item	Criterion					
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:					
		y: Chip width x: Chip length z: Chip thickness					
		$y \le 0.5 \text{mm} \qquad \qquad x \le 1/8 \text{a} \qquad \qquad 0 < z \le t$					
		6.2.2 Non-conductive portion:					
06	Glass	y 12 X X X X	2.5				
		y: Chip width x: Chip length z: Chip thickness					
		$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$					
		<ul> <li>⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</li> <li>⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.</li> <li>6.2.3 Substrate protuberance and internal crack.</li> <li>y: width x: length</li> <li>y ≤ 1/3L x ≤ a</li> </ul>					

NO	Item	Criterion			
07	Cracked glass	The LCD with extensive crack is not acceptable.			
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or colour wrong.</li> </ul>			
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>			
10	PCB、COB	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> <li>10.9 The Scraping testing standard for Copper Coating of PCB</li> </ul>	2.5 2.5 0.65 2.5 2.5 0.65 2.5 2.5 2.5		
11	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.		2.5 2.5 2.5 0.65		

NO	Item	Criterion	AQL
12	General appearance	<ul> <li>12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.</li> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black colour.</li> <li>12.7 Sealant on top of the ITO circuit has not hardened.</li> <li>12.8 Pin type must match type in specification sheet.</li> <li>12.9 LCD pin loose or missing pins.</li> <li>12.10 Product packaging must the same as specified on packaging specification sheet.</li> </ul>	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65
		<ul><li>12.8 Pin type must match type in specification sheet.</li><li>12.9 LCD pin loose or missing pins.</li><li>12.10 Product packaging must the same as specified on packaging</li></ul>	0.65
		specification sheet.	

### 13. Material list of components for RoHS

1. The manufacturer hereby declares that all of or part of products (with the mark "/R" in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in EU-Directive 2002/95/EC.

#### Exhibit A: The harmful material list:

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

### 2. Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than used before.
- (2) Heat-resistance temp.:

Reflow: 250 ℃,30 seconds Max.;

Connector soldering wave or hand soldering: 320 °C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5 °C;

Recommended customer's soldering temp. of connector : 280 ℃, 3 seconds.